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Photosensitive resin composition for a photosensitive elements - comprises a carboxyl-containing binder polymer, a photopolymerisation initiator, and a photopolymerisable unsaturated compound having polymerisable ethylene unsaturated bond(s) in its molecule

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Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 11133595	A	19990521	JP 97294510	A	19971027	199931 B

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Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 11133595	A	7	G03F-007/027	

Abstract (Basic): JP 11133595 A

A photosensitive resin composition comprises: (A) a binder polymer which has a carboxyl group; (B) a photopolymerisation initiator; and (C) a photopolymerisable unsaturated compound which has at least one polymerisable ethylene unsaturated bond in its molecule. (C) the compound contains an ethylene unsaturated compound of formula  $\text{CH}_3\text{CH}_2\text{-C}(\text{CH}_2\text{-O-(A-O)}_{m1}\text{-(B-O)}_{n1}\text{-C(=O)-C(R1)=CH}_2)(\text{CH}_2\text{-O-(A-O)}_{m3}\text{-(B-O)}_{n3}\text{-C(=O)-C(R3)=CH}_2)\text{-CH}_2\text{-O-(A-O)}_{m2}\text{-(B-O)}_{n2}\text{-C(=O)-C(R2)=CH}_2$  (I); where R1, R2, R3 = H or CH3. They may be the same or different; A, B = -CH(CH3)CH2-, -CH2CH(CH3)-, or -CH2CH2-; A and B are different; m1, m2, m3, n1, n2, n3 = a positive integer, where m1 + m2 + m3 = 6 to 45; n1 + n2 + n3 = 3 to 45.

ADVANTAGE - This photosensitive resin composition has excellent anti-plating and peel-off properties.

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Title Terms: PHOTOSENSITISER; RESIN; COMPOSITION; PHOTOSENSITISER; ELEMENT;

COMPRISE; CARBOXYL; CONTAIN; BIND; POLYMER; PHOTOPOLYMERISE; INITIATE;